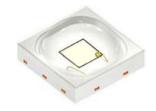
## GV QSSPA1.13

### OSCONIQ® P 3030

The OSCONIQ P 3030 Colors family LED comes with well known superior robustness, high reliability, long lifetime, low thermal resistance. Compact and proven 3mm x 3mm package and established footprint. Perfectly addressing applications that demand for high efficiency and long lifetime.









## **Applications**

- Architecture / Garden Lighting (LED & Laser)
- Medical Illumination

- Photo Therapy
- Stage Lighting (LED & Laser)

### Features:

- Package: SMD epoxy package

- Typ. Radiation: 120°

- Corrosion Robustness Class: 3B

- Lumen maintenance: Test results according to IESNA LM-80 available

- ESD: 8 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 3B)

- Luminous Flux: typ. 90 lm

- Luminous Efficacy: typ. 88 lm/W





Ordering Information		
Туре	Luminous Flux $^{1)}$ I <sub>F</sub> = 350 mA $\Phi_{V}$	Ordering Code
GV QSSPA1.13-JZKZ-V1V6-1	61 112 lm	Q65112A9486



### **GV QSSPA1.13**

Maximum Ratings			
Parameter	Symbol		Values
Operating Temperature	T <sub>op</sub>	min.	-40 °C
	op.	max.	125 °C
Storage Temperature	T <sub>stg</sub>	min.	-40 °C
	0.9	max.	125 °C
Junction Temperature	T <sub>j</sub>	max.	135 °C
Forward current	I <sub>F</sub>	min.	100 mA
	·	max.	1300 mA
Surge Current	I <sub>FS</sub>	max.	2000 mA
$t \le 10 \ \mu s; D = 0.005 ; T_{_J} = 25 \ ^{\circ}C$	10		
Reverse voltage 2)	$V_R$		Not designed for
	T.		reverse operation
ESD withstand voltage	V <sub>ESD</sub>		8 kV
acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 3B)	202		



## **Characteristics**

 $I_F = 350 \text{ mA}; T_J = 25 \text{ }^{\circ}\text{C}$ 

Parameter	Symbol		Values
Peak Wavelength	$\lambda_{\sf peak}$	typ.	492 nm
Dominant Wavelength 3)	$\lambda_{dom}$	min.	480 nm
$I_{\rm r} = 350  \text{mA}$	dolli	typ.	494 nm
		max.	510 nm
Spectral Bandwidth at 50% I <sub>rel,max</sub>	Δλ	typ.	25 nm
Viewing angle at 50% I <sub>v</sub>	2φ	typ.	130 °
Forward Voltage 4)	V <sub>F</sub>	min.	2.60 V
$I_{\rm F} = 350 \text{ mA}$	•	typ.	2.93 V
•		max.	3.00 V
Reverse current 2)	I <sub>R</sub>		Not designed
	TX		for reverse
			operation
Electrical thermal resistance junction/solderpoint with efficiency $\eta_e$ = 42 %	$R_{ ext{thJS elec.}}$	typ.	5.3 K / W



# **Brightness Groups**

Group	Luminous Flux <sup>1)</sup> $I_F = 350 \text{ mA}$ min. $\Phi_V$	Luminous Flux <sup>1)</sup> $I_F = 350 \text{ mA}$ max. $\Phi_V$	
JZ	61 lm	71 lm	
KX	71 lm	82 lm	
KY	82 lm	97 lm	
KZ	97 lm	112 lm	

## **Forward Voltage Groups**

Group	Forward Voltage <sup>4)</sup> I <sub>F</sub> = 350 mA min. V <sub>F</sub>	Forward Voltage <sup>4)</sup> I <sub>F</sub> = 350 mA max. V <sub>F</sub>	
K1	2.60 V	2.70 V	
K2	2.70 V	2.80 V	
L1	2.80 V	2.90 V	
L2	2.90 V	3.00 V	

# **Wavelength Groups**

Group	Dominant Wavelength 3)	Dominant Wavelength 3)
	I <sub>F</sub> = 350 mA	$I_F = 350 \text{ mA}$
	min.	max.
	$\lambda_{\sf dom}$	$\lambda_{\sf dom}$
V1	480 nm	485 nm
V2	485 nm	490 nm
V3	490 nm	495 nm
V4	495 nm	500 nm
V5	500 nm	505 nm
V6	505 nm	510 nm



# **Group Name on Label**

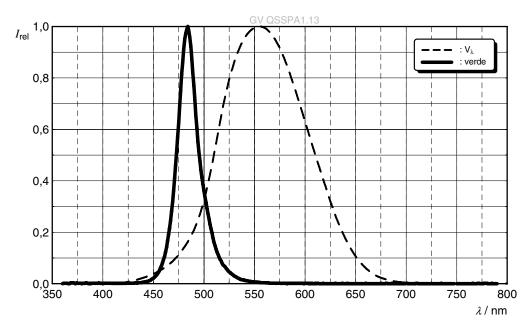
Example: JZ-V1-K1

Brightness	Wavelength	Forward Voltage
JZ	V1	K1



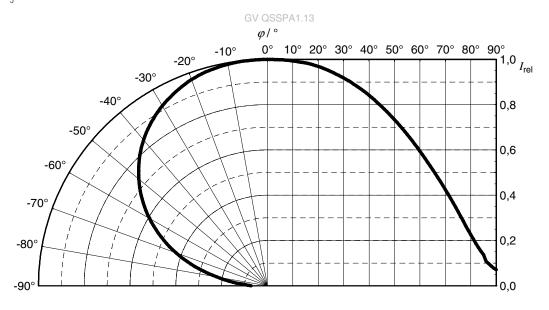
## Relative Spectral Emission 5)

 $I_{rel}$  = f ( $\lambda$ );  $I_F$  = 350 mA;  $T_J$  = 25 °C



## Radiation Characteristics 5)

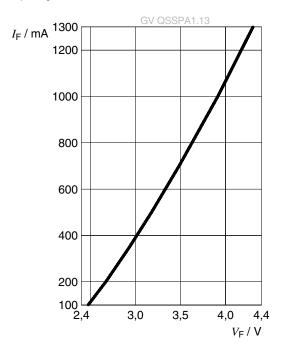
 $I_{rel} = f(\phi); T_J = 25 °C$ 





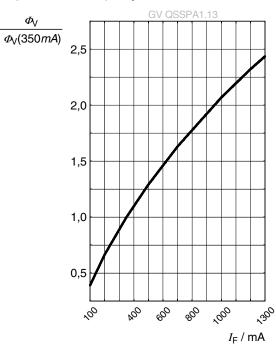
## Forward current 5)

$$I_F = f(V_F); T_J = 25 \, ^{\circ}C$$



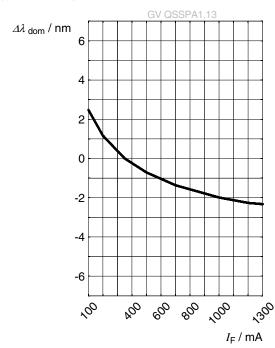
## Relative Luminous Flux 5), 6)

$$\Phi_{V}/\Phi_{V}(350 \text{ mA}) = f(I_{F}); T_{J} = 25 \text{ }^{\circ}\text{C}$$



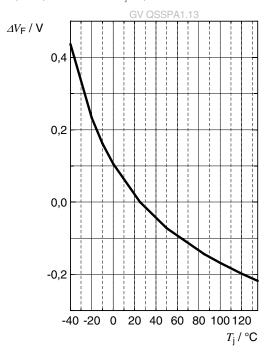
## **Dominant Wavelength** 5)

$$\Delta\lambda_{dom} = f(I_F); T_J = 25 \text{ }^{\circ}\text{C}$$



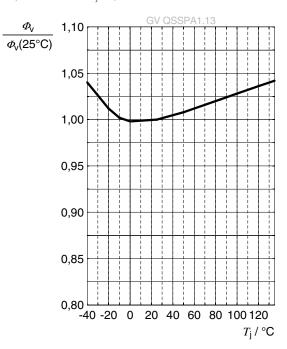
## Forward Voltage 5)

$$\Delta V_{_F} = V_{_F} - V_{_F} (25~^{\circ}\text{C}) = f(T_{_j}); \ I_{_F} = 350~\text{mA}$$



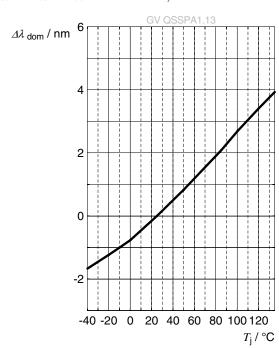
## Relative Luminous Flux 5)

$$\Phi_{v}/\Phi_{v}(25 \text{ °C}) = f(T_{i}); I_{F} = 350 \text{ mA}$$



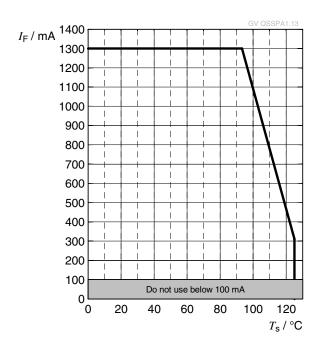
## **Dominant Wavelength** 5)

$$\Delta \lambda_{\text{dom}} = \lambda_{\text{dom}} - \lambda_{\text{dom}} (25 \ ^{\circ}\text{C}) = \text{f(T_j)}; \ \text{I}_{\text{F}} = 350 \ \text{mA}$$



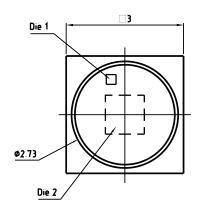
## Max. Permissible Forward Current

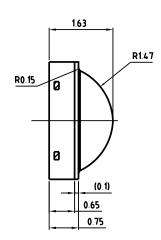
 $I_F = f(T)$ 

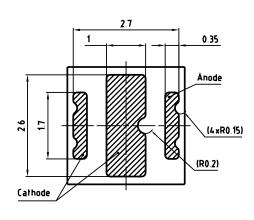




## **Dimensional Drawing** 7)







General tolerance ±0.1 Lead finish Au

C67062-A0282-A1..-07

### **Further Information:**

**Approximate Weight:** 24.0 mg

Package marking: Anode

**Corrosion test:** Class: 3B

Test condition: 40°C / 90 % RH / 15 ppm H<sub>2</sub>S / 14 days (stricter than IEC

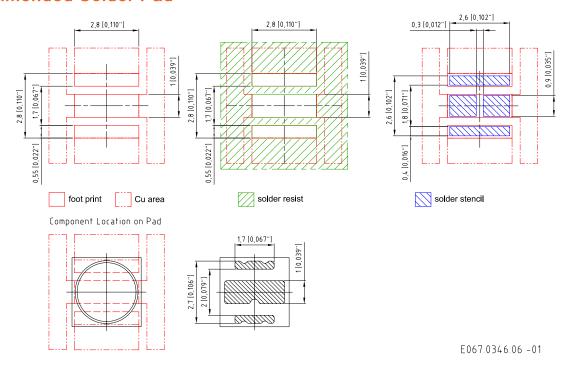
60068-2-43)

The device is protected by ESD device which is connected in parallel to the **ESD** advice:

Chip.



## Recommended Solder Pad 7)

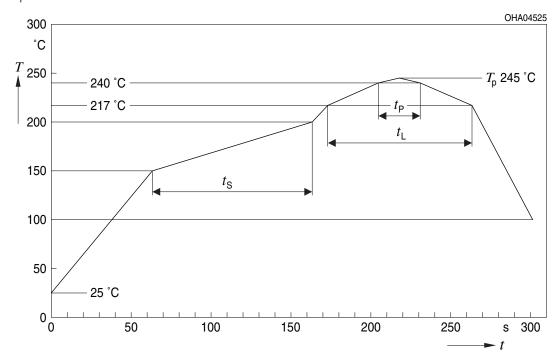


For superior solder joint connectivity results we recommend soldering under standard nitrogen atmosphere. Package not suitable for ultra sonic cleaning.



## **Reflow Soldering Profile**

Product complies to MSL Level 2 acc. to JEDEC J-STD-020E



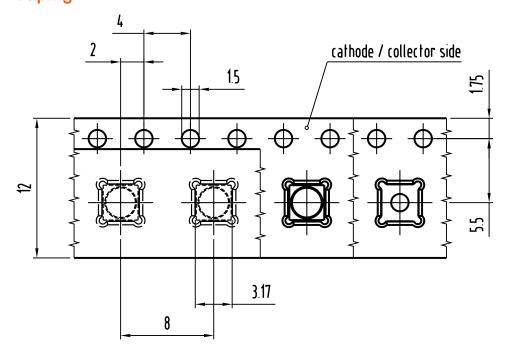
Profile Feature	Symbol	Pb	Pb-Free (SnAgCu) Assembly		
		Minimum	Recommendation	Maximum	
Ramp-up rate to preheat*)			2	3	K/s
25 °C to 150 °C					
Time t <sub>s</sub>	$t_s$	60	100	120	S
$T_{Smin}$ to $T_{Smax}$					
Ramp-up rate to peak*)			2	3	K/s
$T_{Smax}$ to $T_{P}$					
Liquidus temperature	$T_L$		217		°C
Time above liquidus temperature	$t_{\scriptscriptstyle \perp}$		80	100	S
Peak temperature	$T_{P}$		245	260	°C
Time within 5 °C of the specified peak	t <sub>P</sub>	10	20	30	S
temperature T <sub>P</sub> - 5 K					
Ramp-down rate*			3	6	K/s
T <sub>P</sub> to 100 °C					
Time				480	S
25 °C to T <sub>P</sub>					

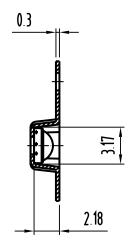
All temperatures refer to the center of the package, measured on the top of the component



<sup>\*</sup> slope calculation DT/Dt: Dt max. 5 s; fulfillment for the whole T-range

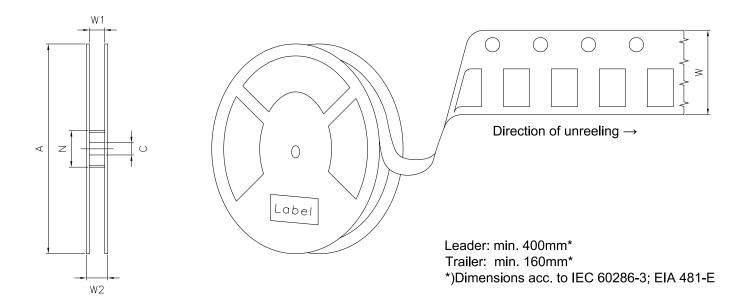
# Taping 7)





C67062-A0282-B7 05

## Tape and Reel 8)



## **Reel Dimensions**

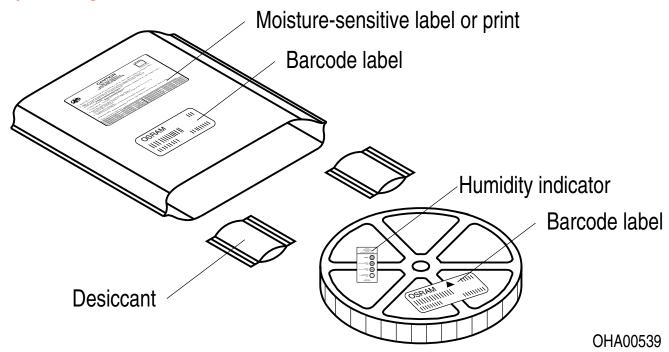
Α	W	$N_{\min}$	W <sub>1</sub>	$W_{2\text{max}}$	Pieces per PU
180 mm	12 + 0.3 / - 0.1 mm	60 mm	12.4 + 2 mm	18.4 mm	600



## **Barcode-Product-Label (BPL)**



## Dry Packing Process and Materials 7)



Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card according JEDEC-STD-033.



#### **Notes**

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the device specified in this data sheet fall into the class **low risk (exposure time 100 s)**. Under real circumstances (for exposure time, conditions of the eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. When looking at bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this device contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize device exposure to aggressive substances during storage, production, and use. Devices that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

This device is designed for specific/recommended applications only. Please consult OSRAM Opto Semiconductors Sales Staff in advance for detailed information on other non-recommended applications (e.g. automotive).

Change management for this component is aligned with the requirements of the lighting market.

For further application related information please visit www.osram-os.com/appnotes



#### **Disclaimer**

#### Attention please!

The information describes the type of component and shall not be considered as assured characteristics. Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.

If printed or downloaded, please find the latest version on the OSRAM OS website.

#### **Packing**

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

#### Product and functional safety devices/applications or medical devices/applications

OSRAM OS components are not developed, constructed or tested for the application as safety relevant component or for the application in medical devices.

OSRAM OS products are not qualified at module and system level for such application.

In case buyer – or customer supplied by buyer – considers using OSRAM OS components in product safety devices/applications or medical devices/applications, buyer and/or customer has to inform the local sales partner of OSRAM OS immediately and OSRAM OS and buyer and /or customer will analyze and coordinate the customer-specific request between OSRAM OS and buyer and/or customer.



## Glossarv

- Brightness: Brightness values are measured during a current pulse of typically 10 ms, with a tolerance of +/- 7%.
- 2) Reverse Operation: Not designed for reverse operation. Continuous reverse operation can cause migration and damage of the device.
- Wavelength: The wavelength is measured at a current pulse of typically 10 ms, with a tolerance of ± 0.5 nm.
- Forward Voltage: The Forward voltage is measured during a current pulse duration of typically 1 ms with a tolerance of  $\pm 0.05V$ .
- Typical Values: Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- Characteristic curve: In the range where the line of the graph is broken, you must expect higher differences between single devices within one packing unit.
- Tolerance of Measure: Unless otherwise noted in drawing, tolerances are specified with ±0.1 and dimensions are specified in mm.
- Tape and Reel: All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.



### GV QSSPA1.13

Revision History					
Version	Date	Change			
1.0	2019-09-05	Initial Version			
1.1	2020-02-19	Schematic Transportation Box Dimensions of Transportation Box			
1.2	2020-11-03	Electro - Optical Characteristics (Diagrams) Reflow Soldering Profile			
1.3	2020-11-23	Applications			
1.3	2021-02-22	Features Ordering Information Brightness Groups			
1.4	2021-07-16	Forward Voltage Groups			



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